2SA1762

Silicon PNP epitaxial planer type

For low-frequency driver amplification Complementary to 2SC4606

Features

- High collector to emitter voltage V_{CEO}.
- Optimum for the driver stage of a low-frequency and 25 to 30W output amplifier.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-80	V
Collector to emitter voltage	V_{CEO}	-80	V
Emitter to base voltage	$V_{\rm EBO}$	-5	V
Peak collector current	I_{CP}	-1	A
Collector current	I_{C}	- 0.5	A
Collector power dissipation	P_{C}^{*}	1	W
Junction temperature	T _j	150	°C
Storage temperature	$T_{\rm stg}$	−55 ~ +150	°C

 $^{^\}ast$ Printed circuit board: Copper foil area of 1cm² or more, and the board thickness of 1.7mm for the collector portion

Unit: mm 6.9±0.1 1.5 R0.9 0.85 0.85±0.1 0.85±0.1 1.8ase 2:Collector EIAJ:SC-71 3:Emitter M Type Mold Package

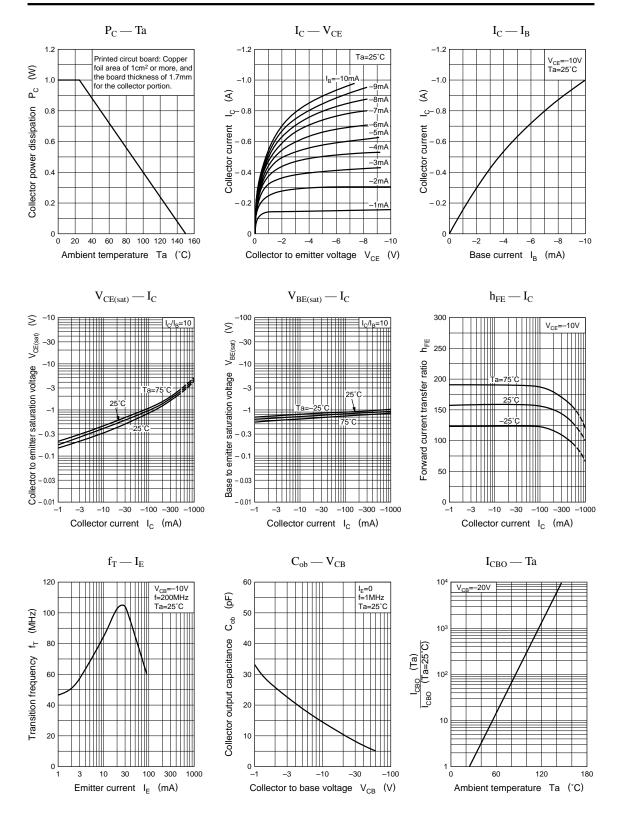
Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -20V, I_E = 0$			- 0.1	μА
Collector to base voltage	V _{CBO}	$I_{\rm C} = -10 \mu A, I_{\rm E} = 0$	-80			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -100 \mu A, I_{\rm B} = 0$	-80			V
Emitter to base voltage	V _{EBO}	$I_{\rm E} = -10\mu A, I_{\rm C} = 0$	-5			V
	h _{FE1} *	$V_{CE} = -10V, I_{C} = -150mA$	130		330	
Forward current transfer ratio	h _{FE2}	$V_{CE} = -5V, I_{C} = -500 \text{mA}$	50	100		
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -300 \text{mA}, I_B = -30 \text{mA}$		- 0.2	- 0.4	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = -300 \text{mA}, I_B = -30 \text{mA}$		- 0.85	-1.2	V
Transition frequency	f_T	$V_{CB} = -10V$, $I_E = 50mA$, $f = 200MHz$		85		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10V, I_E = 0, f = 1 \text{ MHz}$		11	20	pF

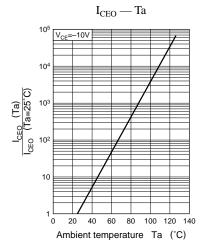
*h_{FE1} Rank classification

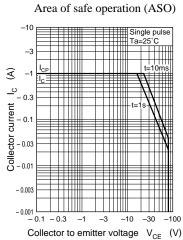
Rank	R	S
h _{FE1}	130 ~ 220	185 ~ 330

Transistor 2SA1762



Transistor 2SA1762





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